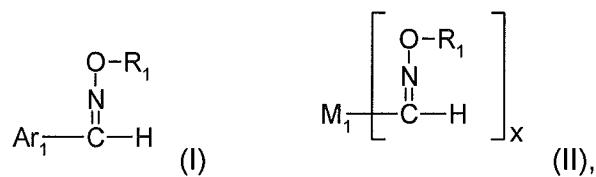


In the Claims

1-3 (cancelled)

4. (currently amended) Alkaline developable, photosensitive composition comprising

(A) at least one alkaline soluble binder resin, prepolymer or monomer component;
(B) at least one compound of formula I or II



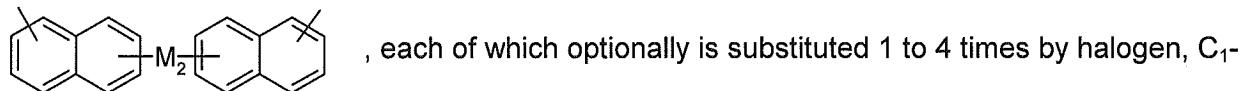
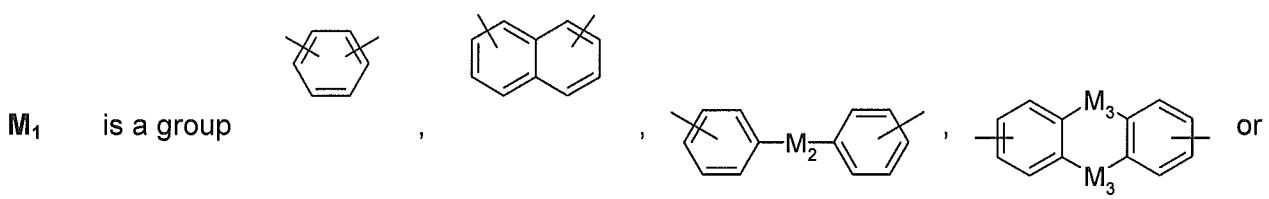
wherein

R_1 is $\text{C}_2\text{-}\text{C}_6$ alkanoyl or $\text{C}_2\text{-}\text{C}_5$ alkoxy carbonyl; or R_1 is benzoyl which is unsubstituted or substituted by one or more $\text{C}_1\text{-}\text{C}_6$ alkyl or halogen;

Ar_1 is phenyl or naphthyl,

each of these radicals is substituted 1 to 5 times by halogen, $\text{C}_1\text{-}\text{C}_{20}$ alkyl, benzyl or $\text{C}_1\text{-}\text{C}_{20}$ alkanoyl; or said phenyl or naphthyl is substituted by phenyl or benzoyl, each of which optionally is substituted by one or more OR_3 , SR_4 or NR_5R_6 ; or said phenyl or naphthyl is substituted by $\text{C}_2\text{-}\text{C}_{12}$ alkoxy carbonyl optionally interrupted by one or more -O- and/or optionally substituted by one or more OH; or said phenyl or naphthyl is substituted by OR_3 , SR_4 or NR_5R_6 , wherein the substituents OR_3 , SR_4 or NR_5R_6 optionally form 5- or 6-membered rings via the radicals R_3 , R_4 , R_5 and/or R_6 with further substituents on the phenyl or naphthyl ring or with one of the carbon atoms of the phenyl or naphthyl ring; or Ar_1 is furyl, pyrrolyl, thienyl, benzofuranyl, indolyl, benzothiophenyl or pyridyl, provided that R_1 is acetyl; wherein each of these radicals is unsubstituted or substituted 1 to 4 times by halogen, $\text{C}_1\text{-}\text{C}_{20}$ alkyl, benzyl, $\text{C}_3\text{-}\text{C}_8$ cycloalkyl, phenyl, $\text{C}_1\text{-}\text{C}_{20}$ alkanoyl, benzoyl, $\text{C}_2\text{-}\text{C}_{12}$ alkoxy carbonyl, phenoxy carbonyl, OR_3 , SR_4 , SOR_4 , SO_2R_4 or NR_5R_6 ;

x is 2;



M₂ is a direct bond, -O-, -S-, -SS-, -NR₃-, -(CO)-, C₁-C₁₂alkylene, phenylene, -(CO)O-(C₂-C₁₂alkylene)-O(CO)-, -(CO)O-(CH₂CH₂O)_n(CO)- or -(CO)-(C₂-C₁₂-alkylene)-(CO)-; or M₂ is C₄-C₁₂alkylene or C₄-C₁₂alkylenedioxy-, each of which is optionally interrupted by 1 to 5 -O-, -S- and/or -NR₃;;

M₃ is a direct bond, -CH₂-, -O-, -S-, -NR₃- or -(CO)-;

R₃ is hydrogen or C₁-C₂₀alkyl; or R₃ is C₂-C₁₂alkyl which is substituted by -OH, -SH, -O(CO)-C₁-C₄alkyl, -O(CO)-phenyl, -(CO)O(C₁-C₄alkyl), -N(C₁-C₄alkyl)₂, -N(CH₂CH₂OH)₂, -N[CH₂CH₂O-(CO)-C₁-C₄alkyl]₂ or morpholinyl; or R₃ is C₂-C₁₂alkyl which is interrupted by one or more -O-; or R₃ is -(CH₂CH₂O)_{n+1}H, -(CH₂CH₂O)_n(CO)-C₁-C₈alkyl, phenyl-C₁-C₃alkyl, C₂-C₈alkanoyl, C₃-C₁₂alkenyl or C₃-C₆alkenoyl; or R₃ is benzoyl which is unsubstituted or substituted by one or more C₁-C₆alkyl, halogen or C₁-C₄alkoxy; or R₃ is phenyl or naphthyl each of which is unsubstituted or substituted by halogen, C₁-C₁₂alkyl, C₁-C₁₂alkoxy, phenyl-C₁-C₃-alkoxy, phenoxy, C₁-C₁₂alkylsulfanyl, phenylsulfanyl, -N(C₁-C₁₂alkyl)₂, diphenylamino or -(CO)R₇;

n is 1 to 20;

R₄ is hydrogen, C₁-C₂₀alkyl, C₃-C₁₂alkenyl, phenyl-C₁-C₃alkyl; C₂-C₈alkyl which is substituted by -OH, -SH, -O(CO)-C₁-C₄alkyl, -O(CO)-phenyl or -(CO)O(C₁-C₄alkyl); or R₄ is C₂-C₁₂alkyl which is interrupted by one or more -O- or -S-; or R₄ is -(CH₂CH₂O)_{n+1}H, -(CH₂CH₂O)_n(CO)-C₁-C₈alkyl, C₂-C₈alkanoyl, C₃-C₁₂alkenyl, C₃-C₆alkenoyl; or R₄ is phenyl or naphthyl each of which is unsubstituted or substituted by halogen, C₁-C₁₂alkyl, C₁-C₁₂alkoxy or -(CO)R₇;

R₅ and **R₆** independently of each other are hydrogen, C₁-C₂₀alkyl, C₂-C₄hydroxyalkyl, C₂-C₁₀alkoxyalkyl, phenyl-C₁-C₃alkyl, C₁-C₄alkanoyl, C₃-C₁₂alkenyl, benzoyl; or are phenyl or naphthyl

each of which is unsubstituted or substituted by C₁-C₁₂alkyl or C₁-C₁₂alkoxy; or R₅ and R₆ together are C₂-C₆alkylene optionally interrupted by -O- or -NR₃- and/or optionally substituted by hydroxyl, C₁-C₄alkoxy, C₂-C₄alkanoyloxy or benzyloxy; and

R₇ is hydrogen, C₁-C₂₀alkyl; or is C₂-C₈alkyl which is substituted by halogen, phenyl, -OH, -SH, C₃-C₆alkenoxy, -O(CO)-C₁-C₄alkyl, -O(CO)-phenyl or -(CO)O(C₁-C₄alkyl); or R₇ is C₂-C₁₂alkyl which is interrupted by one or more -O-; or R₇ is -(CH₂CH₂O)_{n+1}H, -(CH₂CH₂O)_n(CO)-C₁-C₈alkyl or C₃-C₁₂alkenyl; or is phenyl optionally substituted by one or more halogen, C₁-C₁₂alkyl, C₁-C₁₂alkoxy, phenoxy, C₁-C₁₂alkylsulfanyl, phenylsulfanyl, -N(C₁-C₁₂alkyl)₂, or diphenylamino; and

(C) a photopolymerizable compound

and which composition additionally comprises an epoxy compound which contains at least two epoxy groups in the molecule.

5. (currently amended) Photosensitive composition according to claim 4 [[1]], wherein component (B) is a compound of formula I or II, wherein

R₁ is C₂-C₄alkanoyl;

Ar₁ is phenyl or naphthyl, each of which is substituted by halogen, C₁-C₈alkyl, NR₅R₆ or OR₃, wherein the substituents OR₃, optionally form 5- or 6-membered rings via the radicals R₃ with further substituents on the phenyl or naphthyl ring; or provided that R₁ is acetyl, Ar₁ is 2-furyl, 2-pyrrolyl, 2-thienyl, 3-indolyl;



M₁ is ;

x is 2;

R₃ is C₁-C₂₀alkyl; or R₃ is C₂-C₁₂alkyl which is substituted by OH, -O(CO)-C₁-C₄alkyl, -N(C₁-C₄alkyl)₂, -N(CH₂CH₂OH)₂, -N[CH₂CH₂O-(CO)-C₁-C₄alkyl] or morpholinyl; or R₃ is C₂-C₁₂alkyl which is interrupted by one or more -O-; or R₃ is -(CH₂CH₂O)_{n+1}H or -(CH₂CH₂O)_n(CO)-C₁-C₄alkyl;

n is 1 to 3; and

R₅ and R₆ are C₁-C₄alkyl.

6. (currently amended) Photosensitive composition according to claim 4 [[1]], wherein the oligomer or polymer (A) is a binder polymer.

7. (original) Photosensitive composition according to claim 6, wherein the binder polymer is a copolymer of (meth)acrylate and (meth)acrylic acid, or a resin obtained by the reaction of a saturated or unsaturated polybasic acid anhydride with a product of the reaction of an epoxy compound and an unsaturated monocarboxylic acid, or is an addition product formed between a carboxyl group-containing resin and an unsaturated compound having an α,β -unsaturated double bond and an epoxy group.

8. (currently amended) Photosensitive composition according to claim 4 [[1]], which additionally to the components (A), (B) and (C) comprises at least one photosensitizer compound (D).

9. (previously presented) Photosensitive composition according to claim 8, comprising 100 parts by weight of component (A), 0.015 to 120 parts by weight of component (B), 5 to 500 parts by weight of component (C) and 0.015 to 120 parts by weight of component (D).

10. (currently amended) Photosensitive composition according to claim 4 [[1]], comprising further additives (E), which are selected from the group consisting of ~~epoxy compounds~~, thermal polymerization inhibitors, inorganic fillers, colourants, epoxy curing agents, amines, chain transfer agents, thermal radical initiators, photoreducible dyes, optical brighteners, thickeners, antifoaming agents and leveling agents, in particular inorganic fillers.

11. (cancelled)

12. (currently amended) Solder resist comprising a composition according to claim 4 [[1]].

13. (currently amended) Color filter resist comprising a composition according to claim 4 [[1]].

14. (currently amended) Process for the photopolymerization of compounds containing ethylenically unsaturated double bonds, which comprises irradiating a composition according to claim 4 [[1]] with electromagnetic radiation in the range from 150 to 600 nm.

15. (currently amended) Coated substrate which is coated on at least one surface with a composition according to claim 4 [[1]].

16. (original) Process for the production of relief images, wherein a coated substrate according to claim 15 is subjected to imagewise exposure with electromagnetic radiation in the range from 150 to 600 nm, and then the unexposed portions are removed with a solvent.

17. (currently amended) A color filter prepared by providing red, green and blue (RGB) color elements and, optionally a black matrix, all comprising a photosensitive composition according to claim 4 [[1]] and a pigment on a transparent substrate and providing a transparent electrode either on the surface of the substrate or on the surface of the color filter layer.

18. (currently amended) Process for forming images, wherein

- (1) the components of a composition according to claim 4 [[1]] are mixed,
- (2) the resulting composition is applied to the substrate,
- (3) the solvent, if present, is evaporated, at elevated temperature,
- (4) the coated substrate is patternwise exposed to irradiation,
- (5) the irradiated sample is developed with aqueous alkaline solution, thereby removing the uncured areas and
- (6) the sample is thermally cured.

19. (previously presented) Photosensitive composition according to claim 4, wherein compound (A) is an oligomeric or polymeric compound.

20. (previously presented) Photosensitive composition according to claim 4, wherein the photopolymerizable compound (C) is a liquid.